ABSTRACT

A fluid supply nozzle for semiconductor substrate treatment, which supplies a treatment liquid in which a plurality of solutions are mixed to a semiconductor substrate, includes a nozzle body configured to mix the plurality of solutions to form a treatment liquid when the plurality of solutions are supplied into an inner space of the nozzle body, the nozzle body having a shape with an open upper portion, a solution supply channel with a plurality of solution supply pipes for supplying the plurality of solutions to the inner space, a solution guide device configured to guide the plurality of solutions and generate a rotary current or an eddy current to mix the plurality of solutions, and a rotary cartridge configured to accelerate the mixing of the plurality of solutions to generate a homogeneous treatment liquid.

FIG. 5